

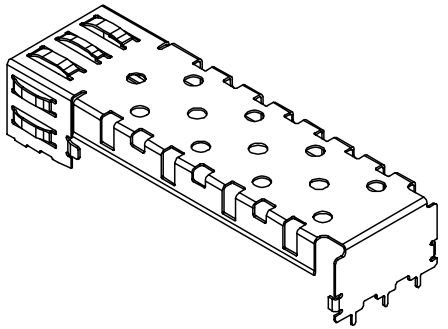

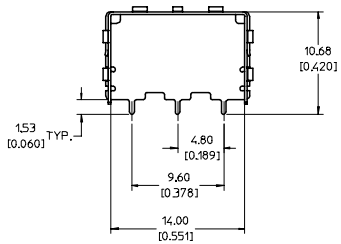

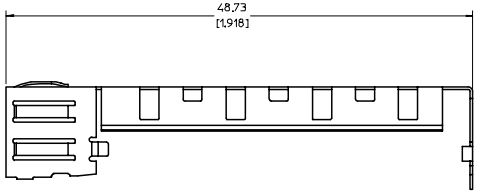

NOTES:

1. MATERIAL: COPPER ALLOY

2. PLATING: BRIGHT TIN
   2.54 MICROMETERS TIN (MIN)
   OVER 0.76 MICROMETERS (MIN) NICKEL

3. FOR DETAILS OF PCB AND BEZEL LAYOUT REFER TO DOCUMENT SD-73927-100.

4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, (RoHS), REFLOW PROCESS. REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C

5. FOR RoHS COMPLIANT REPLACEMENTS REFER TO MOLEX SERIES 74737.

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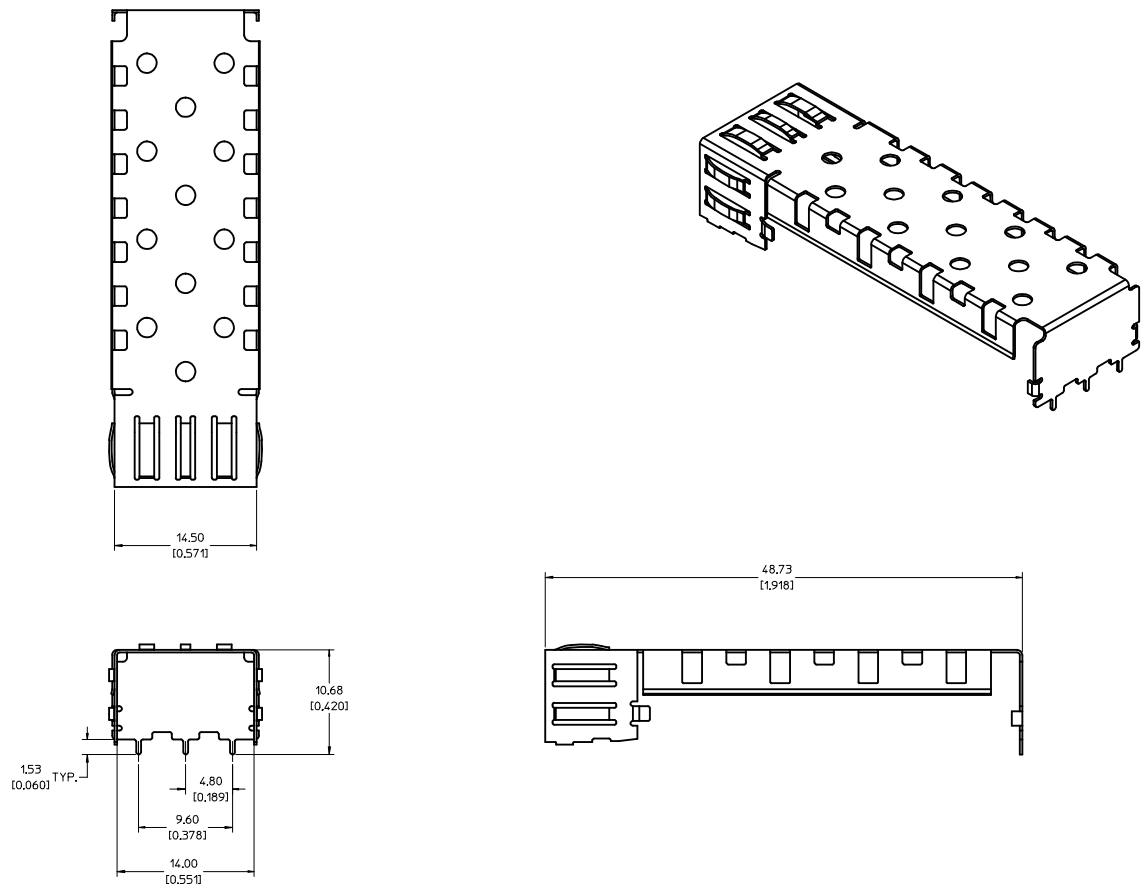

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ENTER DESCRIPTION EC NO: 2006/07/29 DRWN:CCOX 2006/08/07 CHKD: 2006/08/15 APPR:BRUSSELL	QUALITY SYMBOLS ▼=0 C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM/IN	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm / INCH	DRAWN BY KSIMONSON DATE 2005/10/12	TITLE SFP CAGE COVER			
		4 PLACES ± --- ± ---	CHECKED BY BRUSSELL DATE 2005/10/12				
		3 PLACES ± --- ± .005	APPROVED BY BRUSSELL DATE 2005/10/12	molex MOLEX INCORPORATED			
		2 PLACES ± 0.13 ± .01	MATERIAL NO. 739270020	DOCUMENT NO. SD-73927-020	SHEET NO. 1 OF 1		
		1 PLACE ± 0.25 ± ---	SIZE D	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		ANGULAR ± 1 °					
REV B	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

tb_frame_D_P_AM_T
Rev. D 2004/06/28